Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75 (1.6 EP)
Lead Count	12
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.21E-02	86.2	862000	34.99	349878
Thermosets	Epoxy resin	Proprietary	8.40E-04	6.0	60000	2.44	24353
Thermosets	Phenol resin	Proprietary	8.40E-04	6.0	60000	2.44	24353
Other inorganic materials	Metal Hydroxide	Proprietary	2.10E-04	1.5	15000	0.61	6088
Other inorganic materials	Carbon black	1333-86-4	4.20E-05	0.3	3000	0.12	1218
Subtotal			1.40 E-02	100.00	1000000	40.59	405891

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.64 E-02	97.50	975000	47.49	474893
Copper & its alloys	Iron	7439-89-6	3.95 E-04	2.35	23500	1.14	11446
Copper & its alloys	Zinc	7440-66-6	2.02 E-05	0.12	1200	0.06	584
Copper & its alloys	Phosphorus	7723-14-0	5.04 E-06	0.03	300	0.01	146
Subtotal			1.68 E-02	100.00	1000000	48.71	487069

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.20 E-05	100.0	1000000	0.12	1218

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.00 E-04	100.0	1000000	2.32	23194

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.00 E-05	100.0	1000000	0.14	1450

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.60 E-03	100.0	1000000	7.54	75380

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.47 E-04	73.40	734000	0.43	4256
Thermoset	Epoxy Resin	Proprietary	3.67 E-05	18.35	183500	0.11	1064
Other organic materials	Metal oxide	Proprietary	5.50 E-06	2.75	27500	0.02	159
Other organic materials	Amine	Proprietary	5.50 E-06	2.75	27500	0.02	159
Other organic materials	Gamma Butyrolactone	Proprietary	5.50 E-06	2.75	27500	0.02	159
Subtotal			2.00 E-04	100.0	1000000	0.58	5798

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.45 E-02**	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES